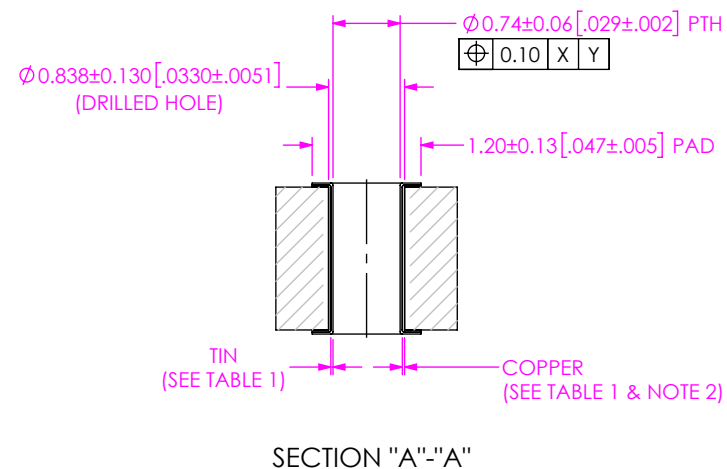
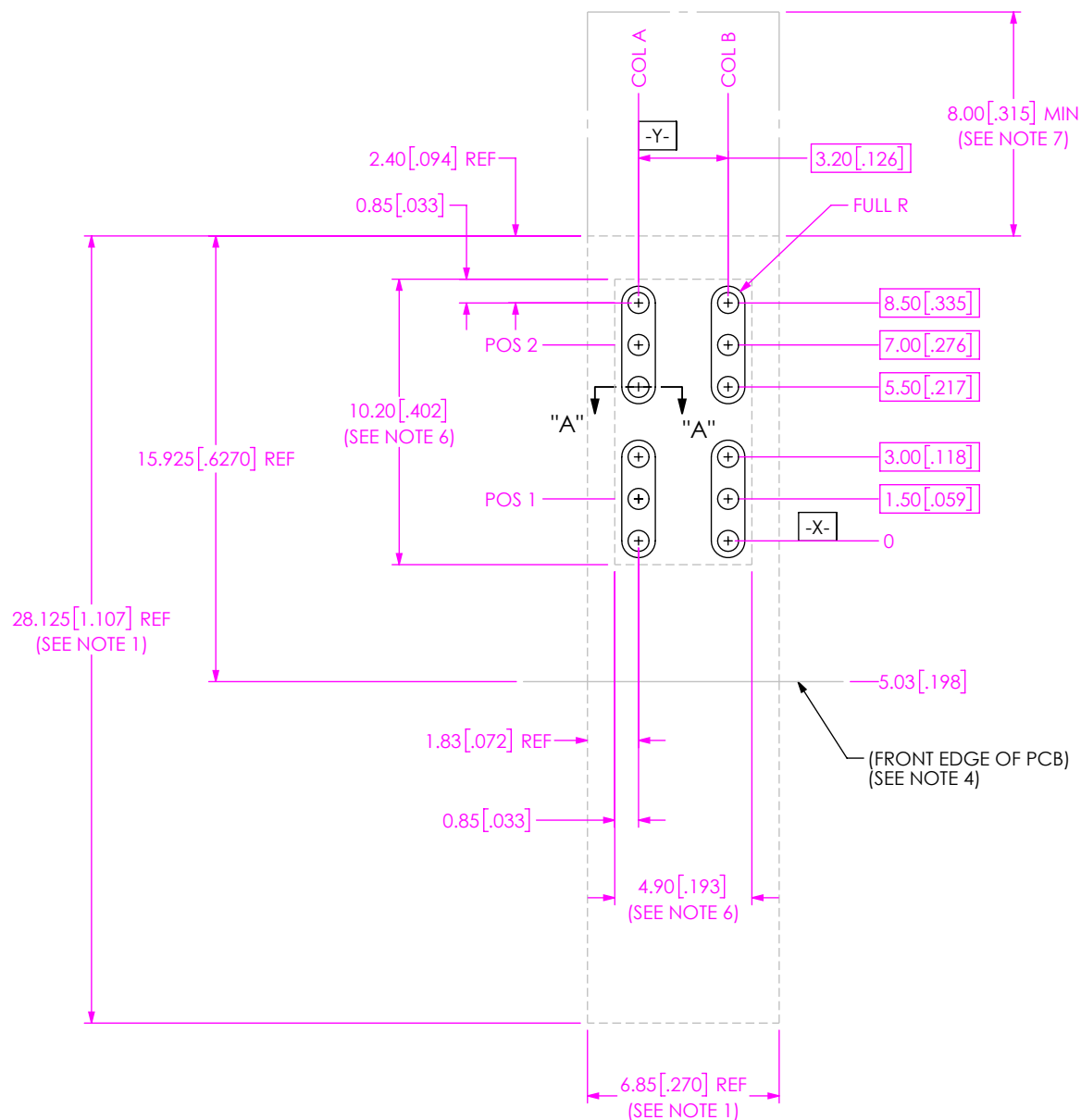




ALL DIMENSIONS ARE SYMMETRIC ABOUT THE CENTERLINE.
(COMPONENT SIDE SHOWN)

TABLE 1

TIN (IMMERSION)	Cu	0.025-0.050 [.0010-.0020]
	Sn	0.001-0.002 [.00004-.00008]

- NOTES:
1. CONNECTOR ENVELOPE DIMENSION. OTHER COMPONENTS PLACED ON PCB SHALL AVOID THIS ZONE.
 2. COPPER THICKNESS MAY NOT VARY MORE THAN 0.02[.001] WITHIN ANY VIA.
 3. CONTACT SAMTEC FOR CONNECTOR PRESS FIT INSTRUCTIONS AND REQUIRED FIXTURES.
 4. MINIMUM BOARD THICKNESS: 1.10 [.043].
 5. REFER TO SAMTEC XCede® HD PRODUCT SPECIFICATION.
 6. NO SURFACE TRACES IN KEEPOUT ZONE.
 7. FOR CONNECTOR REPAIRABILITY, USE KEEPOUT ZONE.

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